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Product Summary

Part Number	R1 (NOM)	R2 (NOM)	Marking
DDTC114ELP	10k Ω	10k Ω	N5

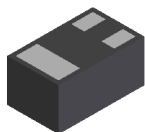
Features

- Epitaxial Planar Die Construction
- Ultra-Small Leadless Surface Mount Package
- Ideally Suited for Automated Assembly Processes
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
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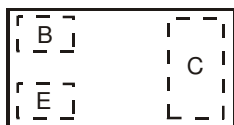
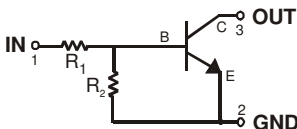
Mechanical Data

- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu
Solderable per MIL-STD-202, Method 208 ^{e4}
- Weight: 0.0009 grams (Approximate)

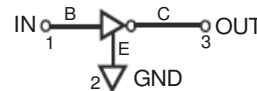
X1-DFN1006-3



Bottom View


 Top View
Pin-Out


Device Symbol


 Equivalent Inverter
Circuit

Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DDTC114ELP-7	N5	7	8	3,000
DDTC114ELP-7B	N5	7	8	10,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information

DDTC114ELP-7	<div style="display: flex; justify-content: space-around;"> <div style="text-align: center;"> <p>Top View Dot Denotes Collector Side</p> </div> <div style="text-align: center;"> <p>From date code 1527 (YYWW), this changes to:</p> <p>Top View Bar Denotes Base and Emitter Side</p> </div> </div>
DDTC114ELP-7B	<div style="text-align: center;"> <p>Top View Bar Denotes Base and Emitter Side</p> </div> <p style="text-align: right;">N5 = Product Type Marking Code</p>

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Supply Voltage	V _{CC}	50	V
Input Voltage	V _{IN}	-10 to +40	V
Output Current	I _O	50	mA
Collector Current	I _{C(MAX)}	100	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	250	mW
Power Derating above +25°C	P _{der}	2	mW/°C
Thermal Resistance, Junction to Ambient Air (Note 5) (Equivalent to one heated junction of NPN)	R _{θJA}	500	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Off Characteristics (Note 6)						
Collector-Base Breakdown Voltage	BV _{CBO}	50	—	—	V	I _C = 50μA, I _E = 0
Collector-Emitter Breakdown Voltage	BV _{CEO}	50	—	—	V	I _C = 1.0mA, I _B = 0
Collector Cutoff Current	I _{CEX}	—	—	0.5	μA	V _{CE} = 50V, V _{EB(OFF)} = 3.0V
Collector-Base Cut Off Current	I _{CBO}	—	—	0.1	μA	V _{CB} = 50V, I _E = 0
Collector-Emitter Cut Off Current, I _{O(OFF)}	I _{CES}	—	—	0.1	μA	V _{CB} = 50V, I _E = 0
Emitter-Base Cut Off Current	I _{EBO}	—	—	800	μA	V _{EB} = 10V, I _C = 0
Input Off Voltage	V _{I(off)}	0.5	1.16	—	V	V _{CC} = 5V, I _O = 100μA
Input On Voltage	V _{I(on)}	—	—	2.5	V	V _{CC} = 0.3V, I _O = 10mA
On Characteristics (Notes 6 & 7)						
DC Current Gain	h _{FE}	10	—	—	—	V _{CE} = 5V, I _C = 1mA
		15	—	—	—	V _{CE} = 5V, I _C = 2mA
		60	—	—	—	V _{CE} = 5V, I _C = 10mA
		100	—	—	—	V _{CE} = 5V, I _C = 50mA
		90	—	—	—	V _{CE} = 5V, I _C = 70mA
Collector-Emitter Saturation Voltage	V _{CE(sat)}	—	—	0.15	V	I _C = 10mA, I _B = 1mA
		—	—	0.2	V	I _C = 50mA, I _B = 5mA
		—	—	0.25	V	I _C = 50mA, I _B = 10mA
		—	—	0.3	V	I _C = 70mA, I _B = 10mA
Base-Emitter Turn-On Voltage	V _{BE(on)}	—	—	0.85	V	V _{CE} = 5V, I _C = 2mA
		—	—	0.95	V	V _{CE} = 5V, I _C = 10mA
Base-Emitter Saturation Voltage	V _{BE(sat)}	—	—	0.98	V	I _C = 10mA, I _B = 1mA
		—	—	1.2	V	I _C = 50mA, I _B = 5mA
Input Current	I _I	—	—	0.88	mA	V _I = 5V
Output On Voltage (Same as V _{CE(sat)})	V _{O(on)}	—	—	0.25	V	I _I = 2.5mA, I _O = 50mA
Input Resistance	R ₁	7	10	13	kΩ	—
Resistance Ratio	(R ₂ /R ₁)	0.8	1	1.2	—	—
Small Signal Characteristics						
Current Gain-Bandwidth Product	f _T	—	250	—	MHz	V _{CE} = 10V, I _E = 5mA, f = 1MHz

Notes: 5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink.

6. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

7. Guaranteed by design.

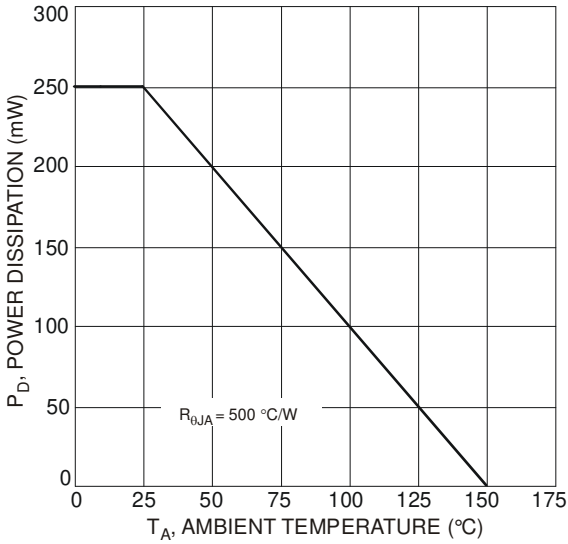


Fig. 1 Power Dissipation vs. Ambient Temperature

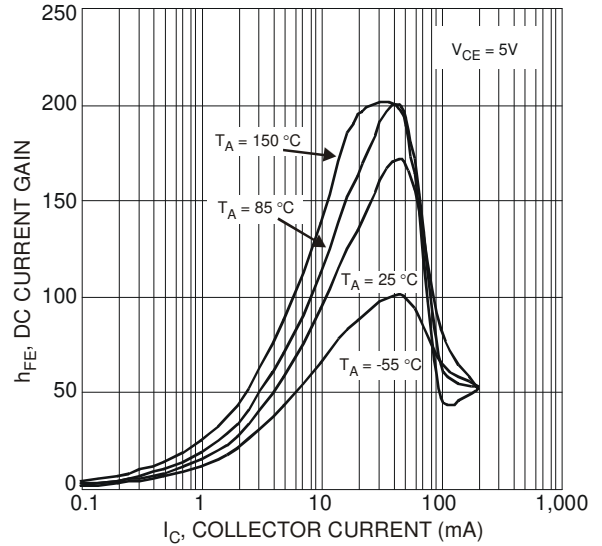


Fig. 2 Typical DC Current Gain vs. Collector Current

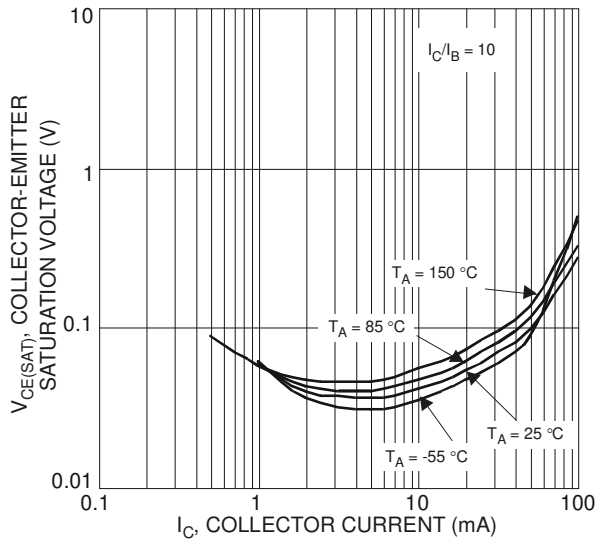


Fig. 3 Typical Collector Emitter Saturation Voltage vs. Collector Current

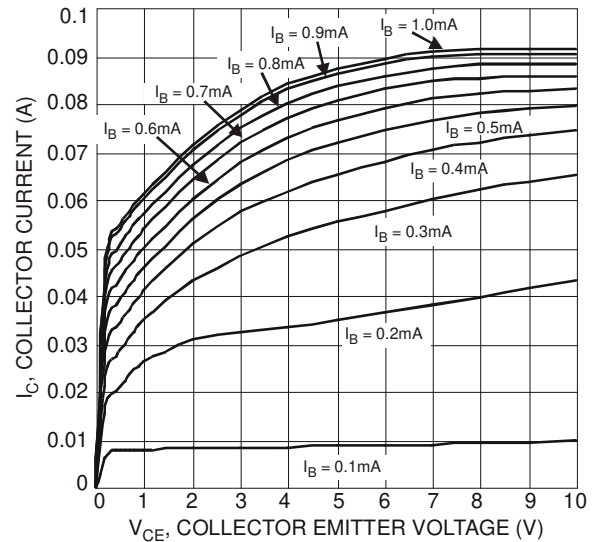


Fig. 4 Typical Collector Current vs. Collector Emitter Voltage

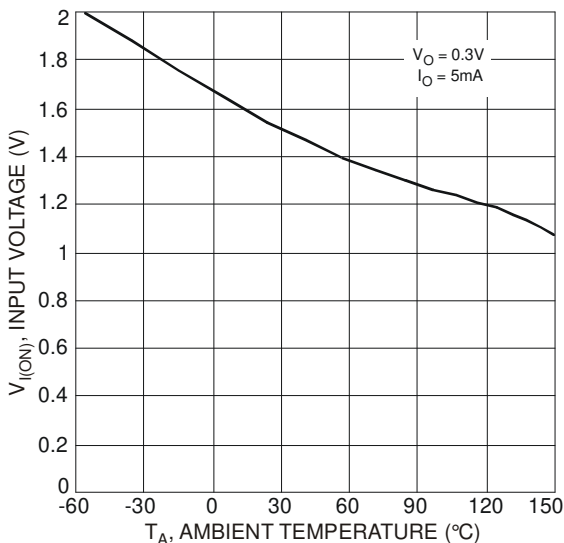


Fig. 5 Typical Input Voltage vs. Ambient Temperature

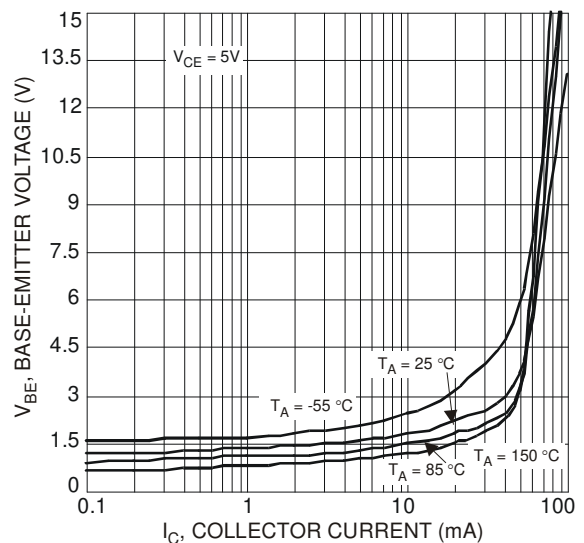


Fig. 6 Typical Base-Emitter Voltage vs. Collector Current

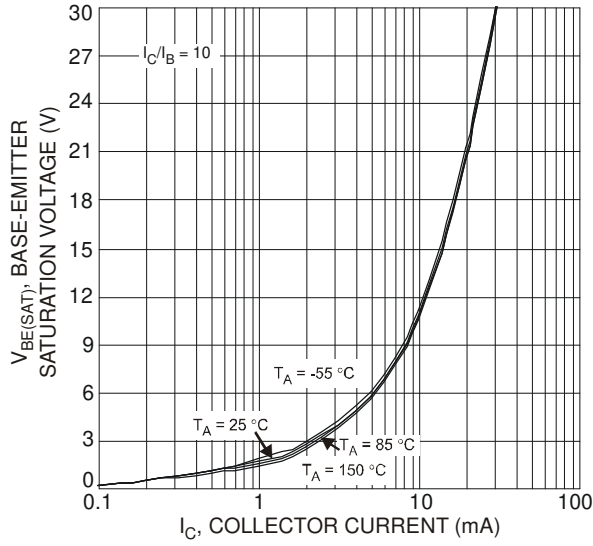


Fig. 7 Typical Base Emitter Saturation Voltage vs. Collector Current

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